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## Product Change Notification - JAON-13SZRI638

**Date:** 09 Oct 2016  
**Product Category:** Memory; Analog (Linear & Mixed Signal) AND Interface; Analog (Thermal, Power Management & Safety)  
**Notification subject:** CCB 1545 Final Notice: Qualification of CuPdAu bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 160K wafer technology available in 8L TDFN package at NSEB site  
**Notification text:** **PCN Status:**  
 Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 160K wafer technology available in 8L TDFN package at NSEB assembly site.

**Pre Change:**

Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB assembly site	NSEB assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	8200T	8600
<b>Molding compound material</b>	G770HCD	G700LTD
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**  
None

**Change Impact:**  
None

**Reason for Change:**  
To improve manufacturability and qualify CuPdAu bond wire, 8600 die attach and G700LTD mold compound material at NSEB assembly site.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
November 25, 2016 (date code: 1647)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	April 2015				->	October 2016				November 2016			
	14	15	16	17		40	41	42	43	44	45	46	47
Workweek													
Initial PCN Issue Date			X										
Qual Report Availability													
Final PCN Issue Date						X							
Estimated Implementation Date													X

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**April 24, 2015:** Issued initial notification.  
**October 9, 2016:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from October 1, 2015 to November 25, 2016. Updated the affected parts list. Updated PCN letter to add the pre and post change summary table and the time table summary. Updated the subject and description to add the die attach and mold compound material.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_JAON-13SZRI638\\_Qual Report.pdf](#)
  - [PCN\\_JAON-13SZRI638\\_Affected\\_CPN.pdf](#)
  - [PCN\\_JAON-13SZRI638\\_Affected\\_CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-13SZRI638
CATALOG_PART_NBR
24AA04HT-I/MNY
24AA04T-I/MNY
24AA08HT-I/MNY
24AA08T-I/MNY
24AA128T-I/MNY
24AA16HT-I/MNY
24AA16T-E/MNY
24AA16T-I/MNY
24AA32AFT-I/MNY
24AA32AT-I/MNY
24AA64FT-I/MNY
24AA64T-E/MNY
24AA64T-I/MNY
24AA64T-I/MNY102
24AA64T-I/MNY104
24AA64T-I/MNY105
24AA64T-I/MNY106
24FC128T-I/MNY
24FC64FT-I/MNY
24FC64T-I/MNY
24LC04BHT-E/MNY
24LC04BHT-I/MNY
24LC04BT-E/MNY
24LC04BT-I/MNY
24LC08BHT-E/MNY
24LC08BHT-I/MNY
24LC08BT-E/MNY
24LC08BT-I/MNY
24LC128T-E/MNY
24LC128T-I/MNY
24LC16BHT-E/MNY
24LC16BHT-I/MNY
24LC16BT-E/MNY
24LC16BT-I/MNY
24LC32AFT-E/MNY
24LC32AFT-I/MNY
24LC32AT-E/MNY
24LC32AT-I/MNY
24LC32AT-I/MNYA29
24LC64FT-E/MNY
24LC64FT-I/MNY
24LC64FT-I/MNY106
24LC64T-E/MNY

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Affected Catalog Part Numbers (CPN)

PCN_JAON-13SZRI638
CATALOG_PART_NBR
24LC64T-I/MNY
25AA010AT-I/MNY
25AA020AT-I/MNY
25AA040AT-I/MNY
25LC010AT-E/MNY
25LC010AT-I/MNY
25LC020AT-E/MNY
25LC020AT-I/MNY
25LC040AT-E/MNY
25LC040AT-I/MNY
34AA04T-E/MNY
34AA04T-I/MNY
MCP6472T-E/MNY
MCP6482T-E/MNY
MCP6492T-E/MNY
MCP6N11T-001E/MNY
MCP6N11T-002E/MNY
MCP6N11T-005E/MNY
MCP6N11T-010E/MNY
MCP6N11T-100E/MNY
MCP6V12T-E/MNY
MCP6V32T-E/MNY
MCP6V62T-E/MNY
MCP6V72T-E/MNY
MCP6V82T-E/MNY
MCP6V92T-E/MNY
MCP98242T-BE/MNY
MCP98242T-BE/MNYAB
MCP98242T-BE/MNYBA2
MCP98242T-BE/MNYBA3
MCP98242T-BE/MNYBAA
MCP98242T-BE/MNYBAC
MCP98242T-BE/MNYBAE
MCP98242T-BE/MNYBAF
MCP98243T-BE/MNY
MCP98243T-BE/MNYAA
MCP98243T-BE/MNYAB
MCP9843T-BE/MNY